

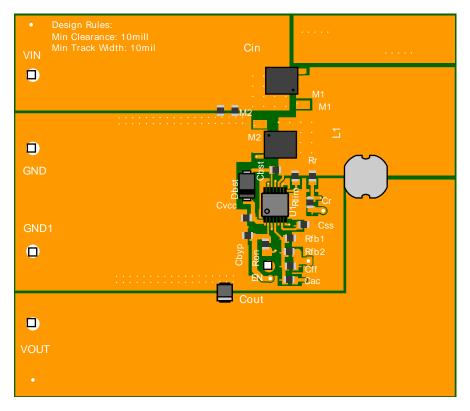
WEBENCH[®] Assembly Document

Design : 4743359/111 LM3150MH/NOPB LM3150MH/NOPB 6.0V-8.4V to 4.20V @ 2.0A

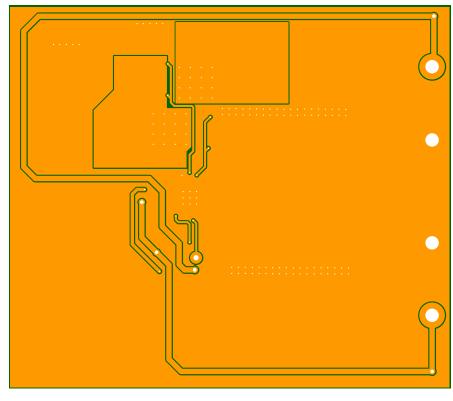
VinMin = 6.0V VinMax = 8.4V Vout = 4.2V Iout = 2.0A Device = LM3150MH/NOPB Topology = Buck Created = 7/18/16 10:53:34 PM BOM Cost = \$3.02 Total Pd = 0.37WFootprint = 361.0 mm^2 BOM Count = 16

General Description

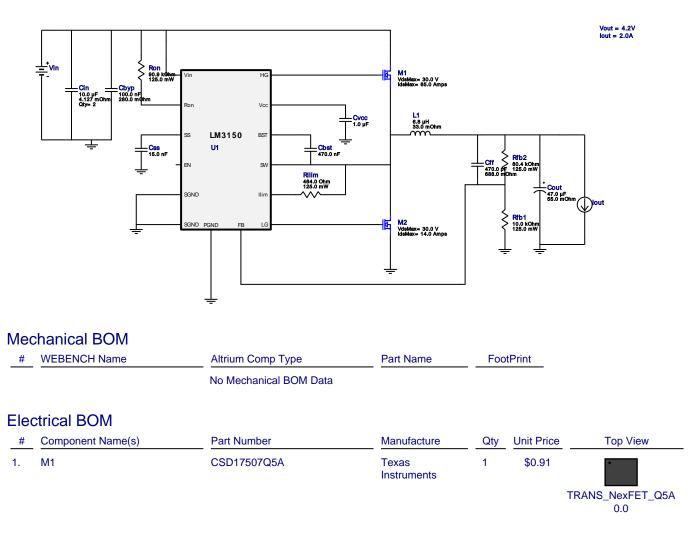
This is a WEBENCH assembly document for LM3150MH/NOPB to support the Build-It Lite feature offered by WEBENCH Power Designer Tool or the full Build-It feature that includes an orderable blank board from our distribution partners. This document serves as a basic guidance on mounting the Build-It kit components onto a blank board and provides the basic setups for testing the fully assembled evaluation module. For more information on the IC performance and other resource, please refer Design Assistance section below.



Top Layer



Bottom Layer



WEBENCH[®] Design

#	Component Name(s)	Part Number	Manufacture	Qty	Unit Price	Top View
2.	L1	SRN8040-6R8Y	Bourns	1	\$0.58	SRN8040 0.0
3.	Rilim	CRCW0805464RFKEA	Vishay-Dale	1	\$0.1	0805 0.0
4.	Сvсс	EMK212B7105KG-T	Taiyo Yuden	1	\$0.3	0805 0.0
5.	Cbst	EMK212B7474KD-T	Taiyo Yuden	1	\$0.28	0805 0.0
6.	Cout	6TPC47M	Panasonic	1	\$1.51	CAPSMT_6_B1G 0.0
7.	Cin	GRM21BR61C106KE15L	MuRata	2	\$0.19	0805 0.0
8.	Cff	C0805C471K5RACTU	Kemet	1	\$0.1	0805 0.0
9.	Rfb1	ERJ-6ENF1002V	Panasonic	1	\$0.1	0805 0.0
10.	Сbyp	08053C104KAT2A	AVX	1	\$0.1	0805 0.0
11.	Css	CC0805KRX7R9BB153	Yageo America	1	\$0.1	0805 0.0
12.	VIN+,VIN-,VOUT+,VOUT-	1502-2	Keystone	4	\$0.34	0.0
13.	U1	LM3150MH/NOPB	Texas Instruments	1	\$3.86	MXA14A 0.0
14.	Ron	ERJ-6ENF9092V	Panasonic	1	\$0.1	0805 0.0
15.	PC Board	551600142-002	Texas Instruments	1	\$0.0	0.0
16.	M2	CSD17579Q5A	Texas Instruments	1	\$0.25	TRANS_NexFET_Q5A 0.0
17.	Rfb2	ERJ-6ENF6042V	Panasonic	1	\$0.1	0805 0.0

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

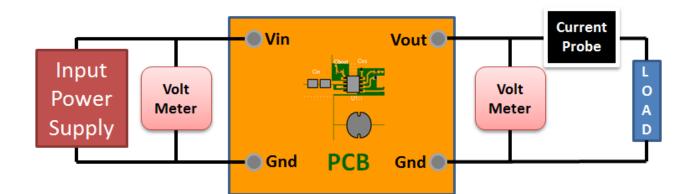
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 6.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Inputs

#	Name	Value	Description		
1.	lout	2.0 A	Maximum Output Current		
2.	VinMax	8.4 V	Maximum input voltage		
3.	VinMin	6.0 V	Minimum input voltage		
4.	Vout	4.2 V	Output Voltage		
5.	base_pn	LM3150	Base Product Number		
6.	source	DC	Input Source Type		
7.	Та	30.0 degC	Ambient temperature		

Design Assistance

1. LM3150 Product Folder : http://www.ti.com/product/LM3150 : contains the data sheet and other resources.

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You should completely validate and test your design implementation to confirm the system functionality for your application prior to production.

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